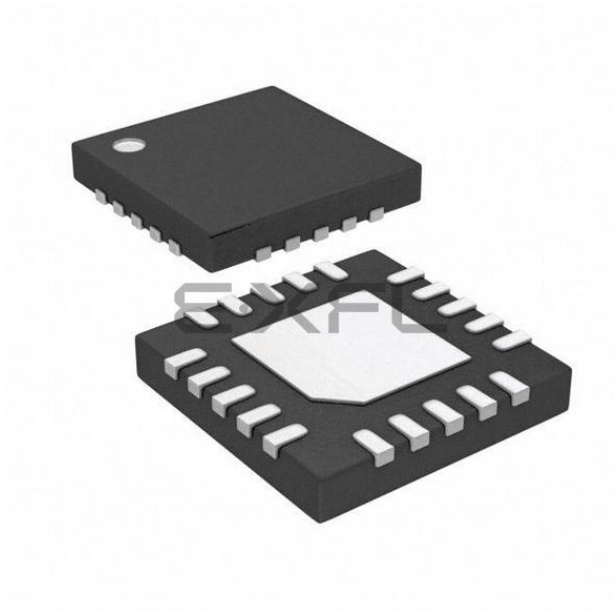


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1829-i-gz

Peripheral Highlights (Continued)

- Data Signal Modulator Module:
  - Selectable modulator and carrier sources
- SR Latch:
  - Multiple Set/Reset input options
  - Emulates 555 Timer applications

PIC12(L)F1822/1840/PIC16(L)F182x/1847 Family Types

Device	Data Sheet Index	Program Memory Flash (words)	Data EEPROM (bytes)	Data SRAM (bytes)	I/O's(2)	10-bit ADC (ch)	CapSense (ch)	Comparators	Timers (8/16-bit)	EUSART	MSSP (I^2C™/SPI)	ECCP (Full-Bridge) ECCP (Half-Bridge) CCP	SR Latch	Debug(1)	XLP
PIC12(L)F1822	(1)	2K	256	128	6	4	4	1	2/1	1	1	0/1/0	Y	I/H	Y
PIC12(L)F1840	(2)	4K	256	256	6	4	4	1	2/1	1	1	0/1/0	Y	I/H	Y
PIC16(L)F1823	(1)	2K	256	128	12	8	8	2	2/1	1	1	1/0/0	Y	I/H	Y
PIC16(L)F1824	(3)	4K	256	256	12	8	8	2	4/1	1	1	1/1/2	Y	I/H	Y
PIC16(L)F1825	(4)	8K	256	1024	12	8	8	2	4/1	1	1	1/1/2	Y	I/H	Y
PIC16(L)F1826	(5)	2K	256	256	16	12	12	2	2/1	1	1	1/0/0	Y	I/H	Y
PIC16(L)F1827	(5)	4K	256	384	16	12	12	2	4/1	1	2	1/1/2	Y	I/H	Y
PIC16(L)F1828	(3)	4K	256	256	18	12	12	2	4/1	1	1	1/1/2	Y	I/H	Y
PIC16(L)F1829	(4)	8K	256	1024	18	12	12	2	4/1	1	2	1/1/2	Y	I/H	Y
PIC16(L)F1847	(6)	8K	256	1024	16	12	12	2	4/1	1	2	1/1/2	Y	I/H	Y

Note 1: I - Debugging, Integrated on Chip; H - Debugging, available using Debug Header.

2: One pin is input-only.

Data Sheet Index: (Unshaded devices are described in this document.)

1: DS41413 PIC12(L)F1822/PIC16(L)F1823 Data Sheet, 8/14-Pin Flash Microcontrollers.

2: DS41441 PIC12(L)F1840 Data Sheet, 8-Pin Flash Microcontrollers.

3: DS41419 PIC16(L)F1824/1828 Data Sheet, 28/40/44-Pin Flash Microcontrollers.

4: DS41440 PIC16(L)F1825/1829 Data Sheet, 14/20-Pin Flash Microcontrollers.

5: DS41391 PIC16(L)F1826/1827 Data Sheet, 18/20/28-Pin Flash Microcontrollers.

6: DS41453 PIC16(L)F1847 Data Sheet, 18/20/28-Pin Flash Microcontrollers.

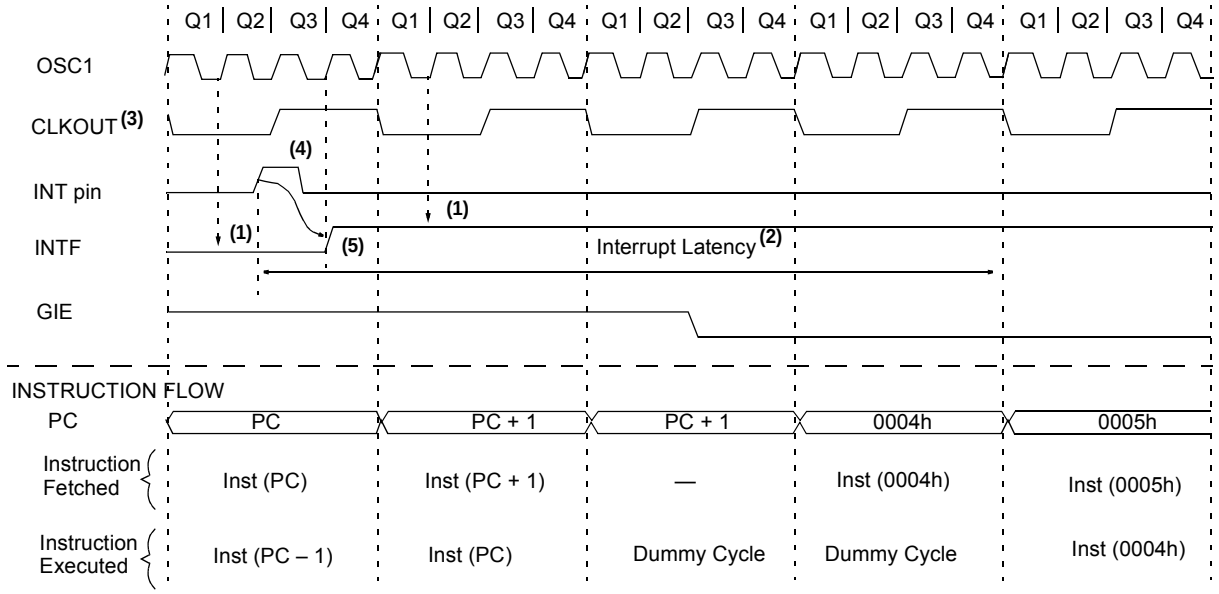
Note: For other small form-factor package availability and marking information, please visit www.microchip.com/packaging or contact your local sales office.

TABLE 3-4: PIC16(L)F1825/9 MEMORY MAP, BANKS 8-15

	BANK 8		BANK 9		BANK 10		BANK 11		BANK 12		BANK 13		BANK 14		BANK 15	
400h	INDF0	480h	INDF0	500h	INDF0	580h	INDF0	600h	INDF0	680h	INDF0	700h	INDF0	780h	INDF0
401h	INDF1	481h	INDF1	501h	INDF1	581h	INDF1	601h	INDF1	681h	INDF1	701h	INDF1	781h	INDF1
402h	PCL	482h	PCL	502h	PCL	582h	PCL	602h	PCL	682h	PCL	702h	PCL	782h	PCL
403h	STATUS	483h	STATUS	503h	STATUS	583h	STATUS	603h	STATUS	683h	STATUS	703h	STATUS	783h	STATUS
404h	FSR0L	484h	FSR0L	504h	FSR0L	584h	FSR0L	604h	FSR0L	684h	FSR0L	704h	FSR0L	784h	FSR0L
405h	FSR0H	485h	FSR0H	505h	FSR0H	585h	FSR0H	605h	FSR0H	685h	FSR0H	705h	FSR0H	785h	FSR0H
406h	FSR1L	486h	FSR1L	506h	FSR1L	586h	FSR1L	606h	FSR1L	686h	FSR1L	706h	FSR1L	786h	FSR1L
407h	FSR1H	487h	FSR1H	507h	FSR1H	587h	FSR1H	607h	FSR1H	687h	FSR1H	707h	FSR1H	787h	FSR1H
408h	BSR	488h	BSR	508h	BSR	588h	BSR	608h	BSR	688h	BSR	708h	BSR	788h	BSR
409h	WREG	489h	WREG	509h	WREG	589h	WREG	609h	WREG	689h	WREG	709h	WREG	789h	WREG
40Ah	PCLATH	48Ah	PCLATH	50Ah	PCLATH	58Ah	PCLATH	60Ah	PCLATH	68Ah	PCLATH	70Ah	PCLATH	78Ah	PCLATH
40Bh	INTCON	48Bh	INTCON	50Bh	INTCON	58Bh	INTCON	60Bh	INTCON	68Bh	INTCON	70Bh	INTCON	78Bh	INTCON
40Ch	—	48Ch	—	50Ch	—	58Ch	—	60Ch	—	68Ch	—	70Ch	—	78Ch	—
40Dh	—	48Dh	—	50Dh	—	58Dh	—	60Dh	—	68Dh	—	70Dh	—	78Dh	—
40Eh	—	48Eh	—	50Eh	—	58Eh	—	60Eh	—	68Eh	—	70Eh	—	78Eh	—
40Fh	—	48Fh	—	50Fh	—	58Fh	—	60Fh	—	68Fh	—	70Fh	—	78Fh	—
410h	—	490h	—	510h	—	590h	—	610h	—	690h	—	710h	—	790h	—
411h	—	491h	—	511h	—	591h	—	611h	—	691h	—	711h	—	791h	—
412h	—	492h	—	512h	—	592h	—	612h	—	692h	—	712h	—	792h	—
413h	—	493h	—	513h	—	593h	—	613h	—	693h	—	713h	—	793h	—
414h	—	494h	—	514h	—	594h	—	614h	—	694h	—	714h	—	794h	—
415h	TMR4	495h	—	515h	—	595h	—	615h	—	695h	—	715h	—	795h	—
416h	PR4	496h	—	516h	—	596h	—	616h	—	696h	—	716h	—	796h	—
417h	T4CON	497h	—	517h	—	597h	—	617h	—	697h	—	717h	—	797h	—
418h	—	498h	—	518h	—	598h	—	618h	—	698h	—	718h	—	798h	—
419h	—	499h	—	519h	—	599h	—	619h	—	699h	—	719h	—	799h	—
41Ah	—	49Ah	—	51Ah	—	59Ah	—	61Ah	—	69Ah	—	71Ah	—	79Ah	—
41Bh	—	49Bh	—	51Bh	—	59Bh	—	61Bh	—	69Bh	—	71Bh	—	79Bh	—
41Ch	TMR6	49Ch	—	51Ch	—	59Ch	—	61Ch	—	69Ch	—	71Ch	—	79Ch	—
41Dh	PR6	49Dh	—	51Dh	—	59Dh	—	61Dh	—	69Dh	—	71Dh	—	79Dh	—
41Eh	T6CON	49Eh	—	51Eh	—	59Eh	—	61Eh	—	69Eh	—	71Eh	—	79Eh	—
41Fh	—	49Fh	—	51Fh	—	59Fh	—	61Fh	—	69Fh	—	71Fh	—	79Fh	—
420h	General Purpose Register 80 Bytes	4A0h	General Purpose Register 80 Bytes	520h	General Purpose Register 80 Bytes	5A0h	General Purpose Register 80 Bytes	620h	General Purpose Register 48 Bytes	6A0h	Unimplemented Read as '0'	720h	Unimplemented Read as '0'	7A0h	Unimplemented Read as '0'
46Fh		4EFh		56Fh		5EFh		64Fh		6EFh		76Fh		7EFh	
								650h	Unimplemented Read as '0'						
								66Fh							
470h	Accesses 70h – 7Fh	4F0h	Accesses 70h – 7Fh	570h	Accesses 70h – 7Fh	5F0h	Accesses 70h – 7Fh	670h	Accesses 70h – 7Fh	6F0h	Accesses 70h – 7Fh	770h	Accesses 70h – 7Fh	7F0h	Accesses 70h – 7Fh
47Fh		4FFh		57Fh		5FFh		67Fh		6FFh		77Fh		7FFh	

Legend: = Unimplemented data memory locations, read as '0'

FIGURE 8-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 30.0 "Electrical Specifications"**.

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

12.3 PORTB Registers (PIC16(L)F1829 only)

PORTB is a 4-bit wide, bidirectional port. The corresponding data direction register is TRISB (Register 12-10). Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 12-2 shows how to initialize a port.

Reading the PORTB register (Register 12-9) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATB).

The TRISB register (Register 12-10) controls the PORTB pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISB register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

The INLVLB register (Register 12-14) controls the input voltage threshold for each of the available PORTB input pins. A selection between the Schmitt Trigger CMOS or the TTL Compatible thresholds is available. The input threshold is important in determining the value of a read of the PORTB register and also the level at which an Interrupt-on-Change occurs, if that feature is enabled. See **Section 30.4 "DC Characteristics: PIC16(L)F1825/9-I/E"** for more information on threshold levels.

Note:	Changing the input threshold selection should be performed while all peripheral modules are disabled. Changing the threshold level during the time a module is active may inadvertently generate a transition associated with an input pin, regardless of the actual voltage level on that pin.

12.3.1 ANSELB REGISTER

The ANSELB register (Register 12-12) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELB bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELB bits has no effect on digital output functions. A pin with TRIS clear and ANSELB set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELB bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.

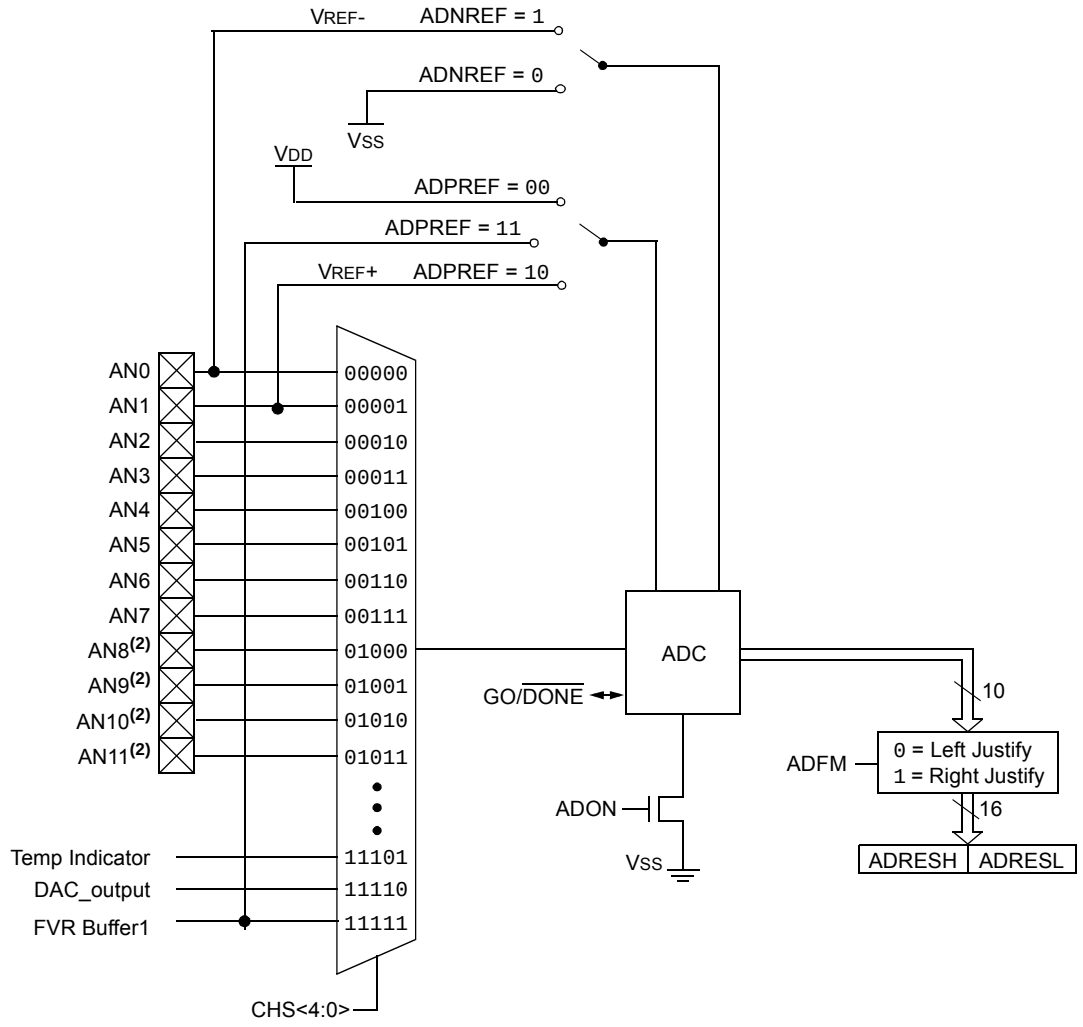
16.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 16-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 16-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.

2: PIC16(L)F1829 only.

23.5 Carrier Source Polarity Select

The signal provided from any selected input source for the carrier high and carrier low signals can be inverted. Inverting the signal for the carrier high source is enabled by setting the MDCHPOL bit of the MDCARH register. Inverting the signal for the carrier low source is enabled by setting the MDCLPOL bit of the MDCARL register.

23.6 Carrier Source Pin Disable

Some peripherals assert control over their corresponding output pin when they are enabled. For example, when the CCP1 module is enabled, the output of CCP1 is connected to the CCP1 pin.

This default connection to a pin can be disabled by setting the MDCHODIS bit in the MDCARH register for the carrier high source and the MDCLODIS bit in the MDCARL register for the carrier low source.

23.7 Programmable Modulator Data

The MDBIT of the MDCON register can be selected as the source for the modulator signal. This gives the user the ability to program the value used for modulation.

23.8 Modulator Source Pin Disable

The modulator source default connection to a pin can be disabled by setting the MDMSODIS bit in the MDSRC register.

23.9 Modulated Output Polarity

The modulated output signal provided on the MDOUT pin can also be inverted. Inverting the modulated output signal is enabled by setting the MDOPOL bit of the MDCON register.

23.10 Slew Rate Control

The slew rate limitation on the output port pin can be disabled. The slew rate limitation can be removed by clearing the MDSLR bit in the MDCON register.

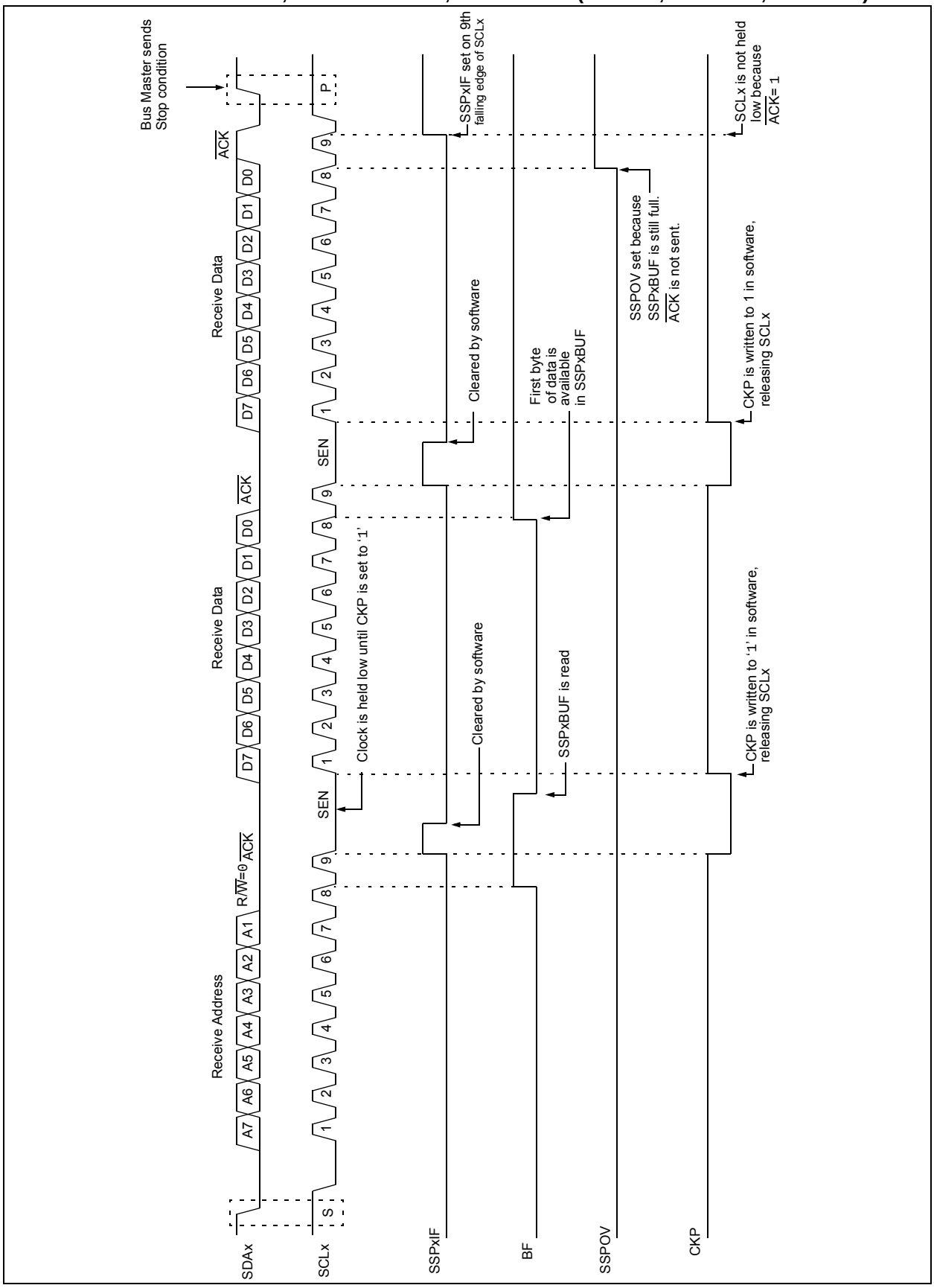
23.11 Operation in Sleep Mode

The DSM module is not affected by Sleep mode. The DSM can still operate during Sleep, if the Carrier and Modulator input sources are also still operable during Sleep.

23.12 Effects of a Reset

Upon any device Reset, the DSM module is disabled. The user's firmware is responsible for initializing the module before enabling the output. The registers are reset to their default values.

FIGURE 25-15: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 1, AHEN = 0, DHEN = 0)



REGISTER 25-2: SSPxCON1: SSPx CONTROL REGISTER 1

R/C/HS-0/0	R/C/HS-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
WCOL	SSPOV	SSPEN	CKP	SSPM<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets	
'1' = Bit is set	'0' = Bit is cleared	HS = Bit is set by hardware	C = User cleared

bit 7 **WCOL:** Write Collision Detect bit
Master mode:
1 = A write to the SSPxBUF register was attempted while the I^2C conditions were not valid for a transmission to be started
0 = No collision
Slave mode:
1 = The SSPxBUF register is written while it is still transmitting the previous word (must be cleared in software)
0 = No collision

bit 6 **SSPOV:** Receive Overflow Indicator bit(1)
In SPI mode:
1 = A new byte is received while the SSPxBUF register is still holding the previous data. In case of overflow, the data in SSPxSR is lost. Overflow can only occur in Slave mode. In Slave mode, the user must read the SSPxBUF, even if only transmitting data, to avoid setting overflow. In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPxBUF register (must be cleared in software).
0 = No overflow
In I^2C mode:
1 = A byte is received while the SSPxBUF register is still holding the previous byte. SSPOV is a "don't care" in Transmit mode (must be cleared in software).
0 = No overflow

bit 5 **SSPEN:** Synchronous Serial Port Enable bit
In both modes, when enabled, these pins must be properly configured as input or output
In SPI mode:
1 = Enables serial port and configures SCKx, SDOx, SDIx and $\overline{SSx}$ as the source of the serial port pins(2)
0 = Disables serial port and configures these pins as I/O port pins
In I^2C mode:
1 = Enables the serial port and configures the SDAx and SCLx pins as the source of the serial port pins(3)
0 = Disables serial port and configures these pins as I/O port pins

bit 4 **CKP:** Clock Polarity Select bit
In SPI mode:
1 = Idle state for clock is a high level
0 = Idle state for clock is a low level
In I^2C Slave mode:
SCLx release control
1 = Enable clock
0 = Holds clock low (clock stretch). (Used to ensure data setup time.)
In I^2C Master mode:
Unused in this mode

bit 3-0 **SSPM<3:0>:** Synchronous Serial Port Mode Select bits
0000 = SPI Master mode, clock = FOSC/4
0001 = SPI Master mode, clock = FOSC/16
0010 = SPI Master mode, clock = FOSC/64
0011 = SPI Master mode, clock = TMR2 output/2
0100 = SPI Slave mode, clock = SCKx pin, $\overline{SSx}$ pin control enabled
0101 = SPI Slave mode, clock = SCKx pin, $\overline{SSx}$ pin control disabled, $\overline{SSx}$ can be used as I/O pin
0110 = I^2C Slave mode, 7-bit address
0111 = I^2C Slave mode, 10-bit address
1000 = I^2C Master mode, clock = FOSC / (4 * (SSPxADD+1))(4)
1001 = Reserved
1010 = SPI Master mode, clock = FOSC/(4 * (SSPxADD+1))(5)
1011 = I^2C firmware controlled Master mode (Slave Idle)
1100 = Reserved
1101 = Reserved
1110 = I^2C Slave mode, 7-bit address with Start and Stop bit interrupts enabled
1111 = I^2C Slave mode, 10-bit address with Start and Stop bit interrupts enabled

Note 1: In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPxBUF register.
2: When enabled, these pins must be properly configured as input or output.
3: When enabled, the SDAx and SCLx pins must be configured as inputs.
4: SSPxADD values of 0, 1 or 2 are not supported for I^2C Mode.
5: SSPxADD value of '0' is not supported. Use SSPM = 0000 instead.

26.3.4 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 '0' bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXSTA register. The Break character transmission is then initiated by a write to the TXREG. The value of data written to TXREG will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXSTA register indicates when the transmit operation is active or Idle, just as it does during normal transmission. See Figure 26-9 for the timing of the Break character sequence.

26.3.4.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to enable the Break sequence.
3. Load the TXREG with a dummy character to initiate transmission (the value is ignored).
4. Write '55h' to TXREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

26.3.5 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCSTA register and the Received data as indicated by RCREG. The Baud Rate Generator is assumed to have been initialized to the expected baud rate.

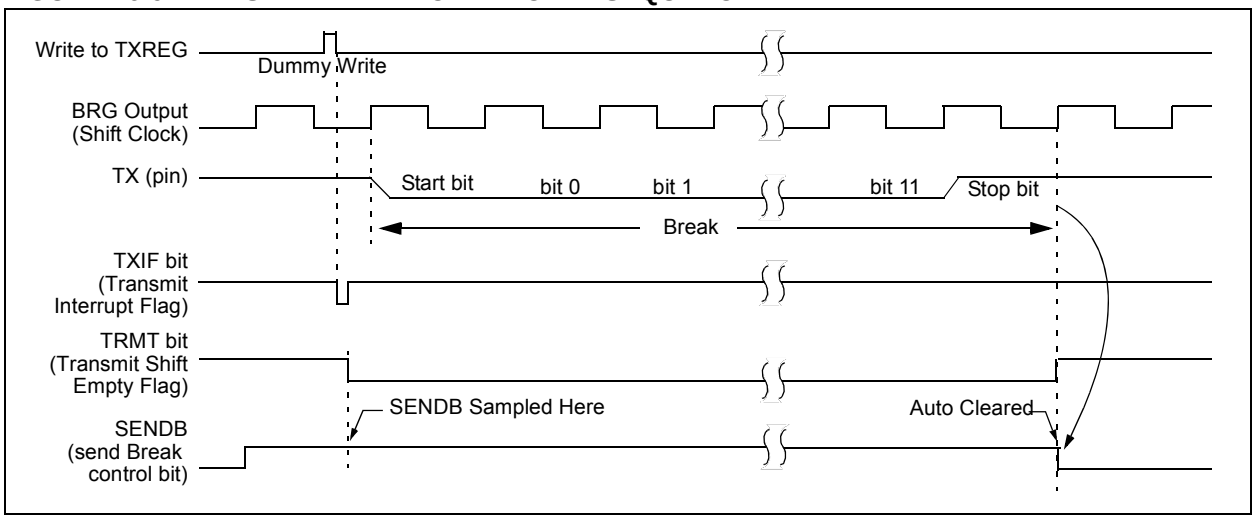
A Break character has been received when;

- RCIF bit is set
- FERR bit is set
- RCREG = 00h

The second method uses the Auto-Wake-up feature described in **Section 26.3.3 "Auto-Wake-up on Break"**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDCON register before placing the EUSART in Sleep mode.

FIGURE 26-9: SEND BREAK CHARACTER SEQUENCE



26.4.1.5 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver is automatically disabled when the EUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are unread characters in the receive FIFO.

Note:	If the RX/DT function is on an analog pin, the corresponding ANSEL bit must be cleared for the receiver to function.

26.4.1.6 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver is automatically disabled when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

Note:	If the device is configured as a slave and the TX/CK function is on an analog pin, the corresponding ANSEL bit must be cleared.

26.4.1.7 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG. If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

26.4.1.8 Receiving 9-bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set the EUSART will shift 9-bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

26.4.1.9 Synchronous Master Reception Setup:

1. Initialize the SPBRGH, SPBRGL register pair for the appropriate baud rate. Set or clear the BRGH and BRG16 bits, as required, to achieve the desired baud rate.
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
4. Ensure bits CREN and SREN are clear.
5. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
6. If 9-bit reception is desired, set bit RX9.
7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
8. Interrupt flag bit RCIF will be set when reception of a character is complete. An interrupt will be generated if the enable bit RCIE was set.
9. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
10. Read the 8-bit received data by reading the RCREG register.
11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

FIGURE 30-3: HFINTOSC FREQUENCY ACCURACY OVER DEVICE VDD AND TEMPERATURE

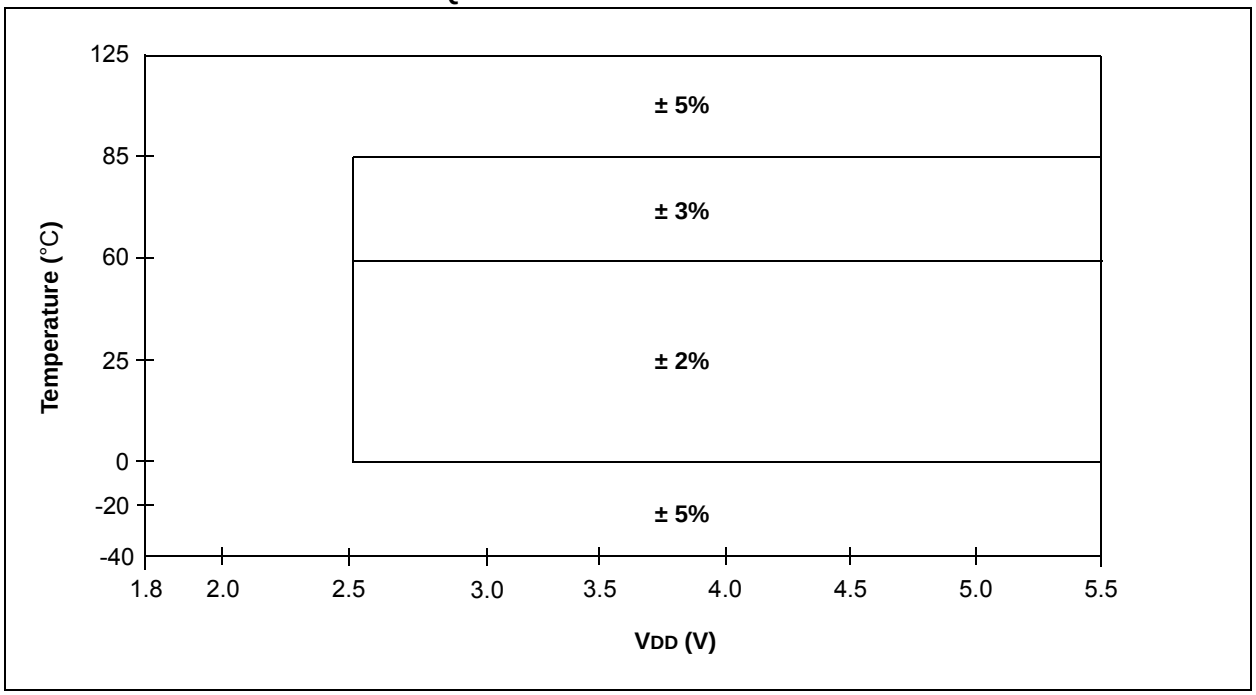


TABLE 30-21: DC CHARACTERISTICS FOR IPD SPECIFICATIONS FOR PIC16F1825/9-H (High Temp.)

PIC16F1825/9		Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Device Characteristics	Min.	Typ.	Max.	Units	Condition	
						VDD	Note
	Power-Down Base Current (IPD)(2)						
D020E		—	0.05	12	µA	2.0	IPD Base
		—	0.15	13	µA	3.0	
		—	0.35	14	µA	5.0	
D021E		—	0.5	20	µA	2.0	WDT Current
		—	2.5	25	µA	3.0	
		—	9.5	36	µA	5.0	
D022E		—	5.0	28	µA	3.0	BOR Current
		—	6.0	36	µA	5.0	
D023E		—	105	195	µA	2.0	IPD Current (both comparators enabled)
		—	110	210	µA	3.0	
		—	116	220	µA	5.0	
		—	50	105	µA	2.0	IPD Current (one comparator enabled)
		—	55	110	µA	3.0	
		—	60	125	µA	5.0	
D024E		—	30	58	µA	2.0	IPD (CVREF, high range)
		—	45	85	µA	3.0	
		—	75	142	µA	5.0	
D025E		—	39	76	µA	2.0	IPD (CVREF, low range)
		—	59	114	µA	3.0	
		—	98	190	µA	5.0	
D026E		—	5.5	30	µA	2.0	IPD (T1 OSC, 32 kHz)
		—	7.0	35	µA	3.0	
		—	8.5	45	µA	5.0	
D027E		—	0.2	12	µA	3.0	IPD (ADC on, not converting)
		—	0.3	15	µA	5.0	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rage, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: A/D oscillator source is FRC.

FIGURE 31-3: IDD TYPICAL, XT AND EXTRC OSCILLATOR, PIC16LF1825/9 ONLY

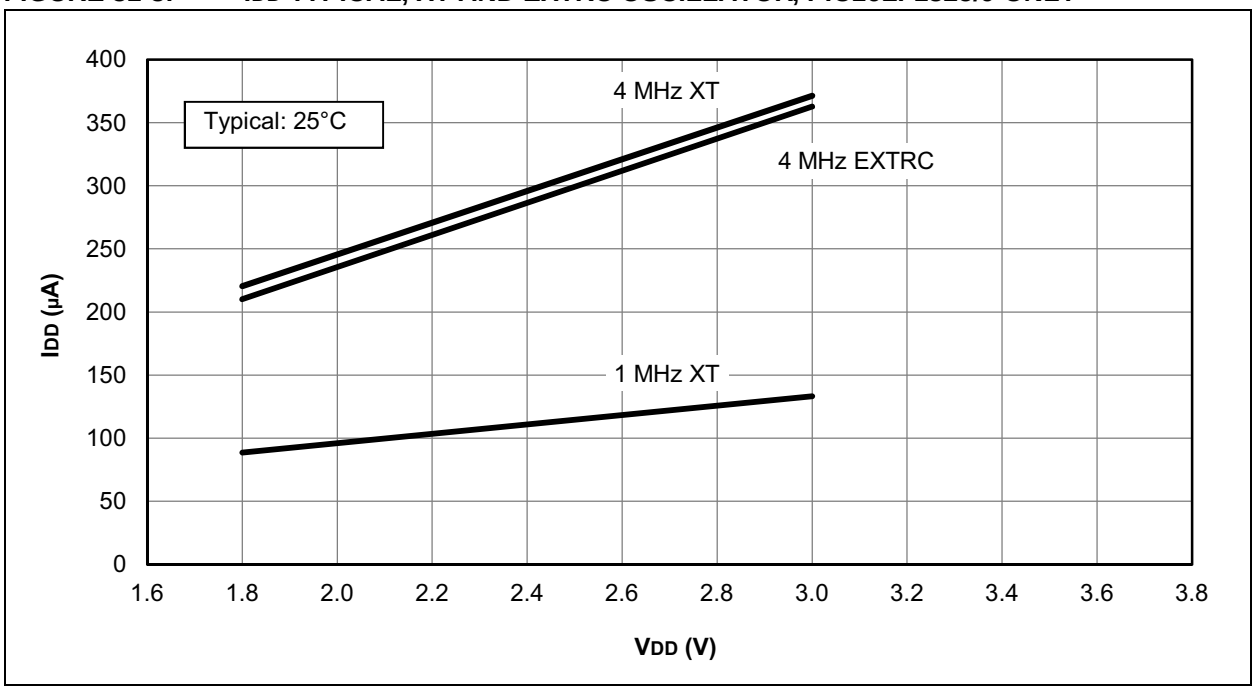


FIGURE 31-4: IDD MAXIMUM, XT AND EXTRC OSCILLATOR, PIC16LF1825/9 ONLY

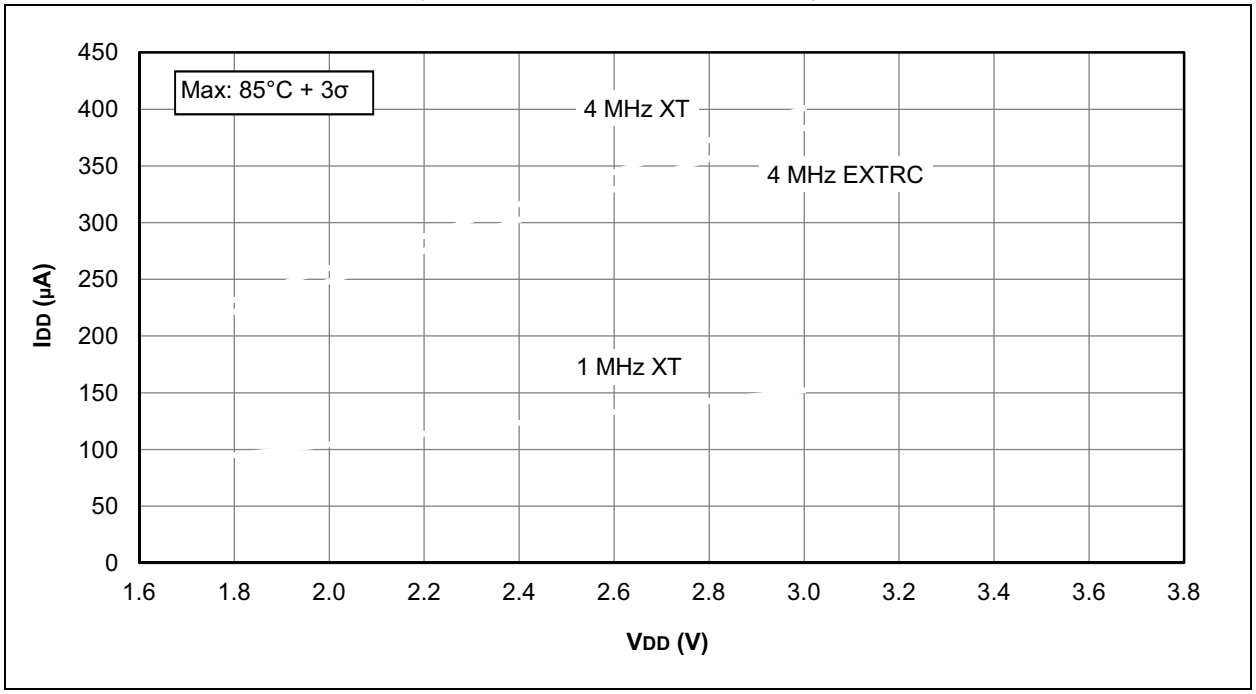


FIGURE 31-5: IDD TYPICAL, XT AND EXTRC OSCILLATOR, PIC16F1825/9 ONLY

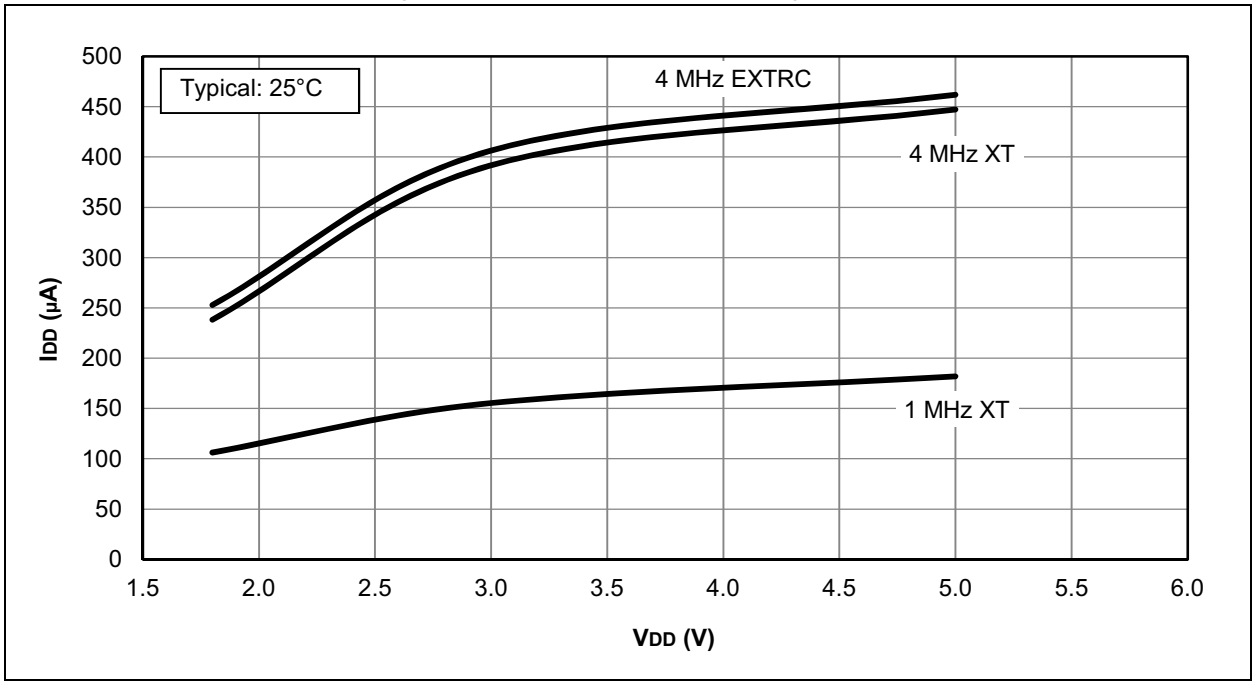


FIGURE 31-6: IDD MAXIMUM, XT AND EXTRC OSCILLATOR, PIC16F1825/9 ONLY

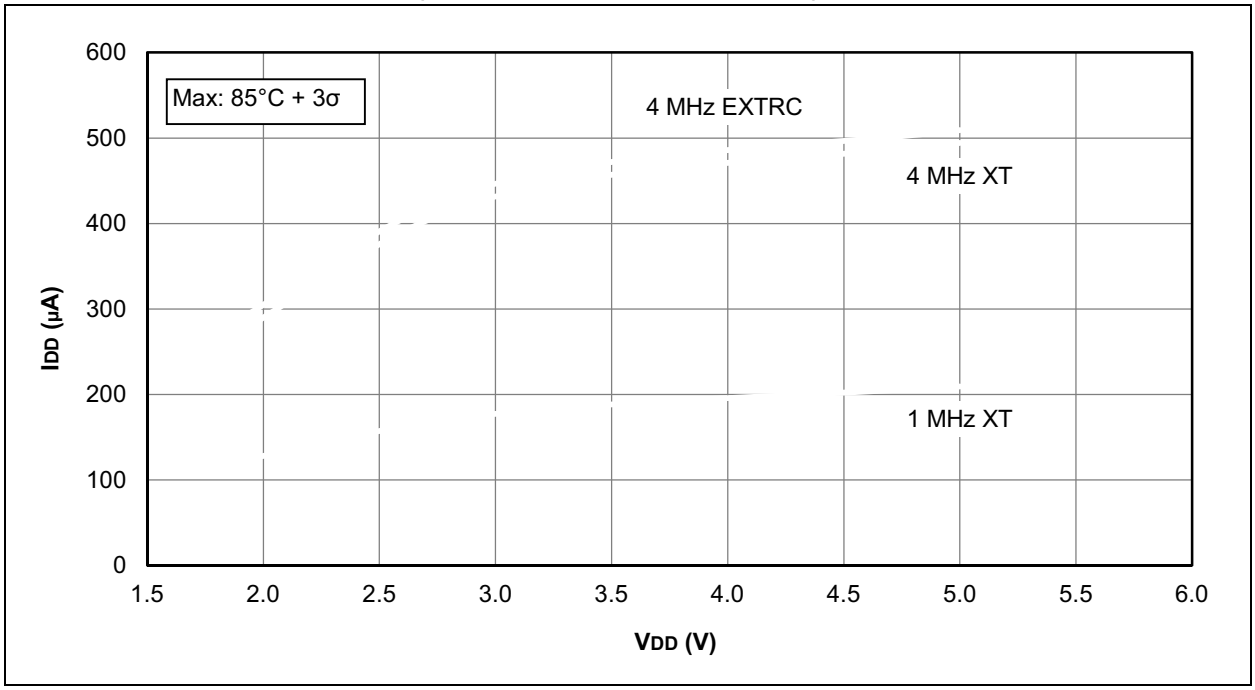


FIGURE 31-43: VOH vs. IOH OVER TEMPERATURE (VDD = 3.0V)

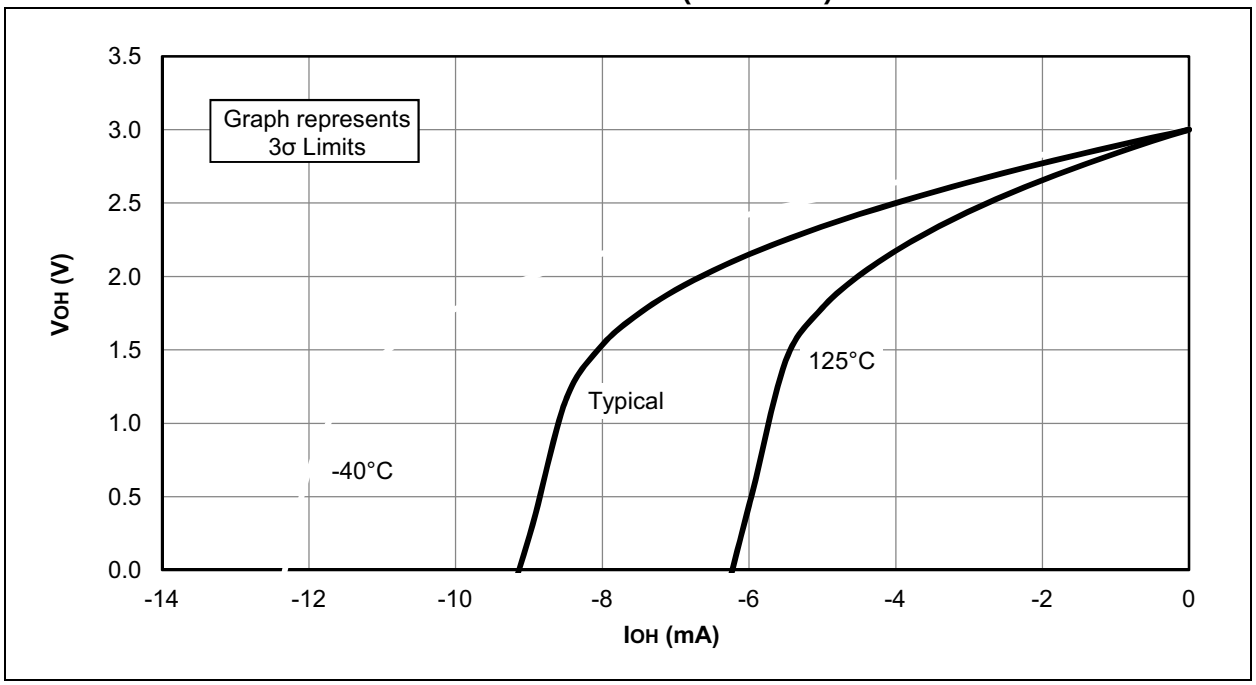


FIGURE 31-44: VOL vs. IOL OVER TEMPERATURE (VDD = 3.0V)

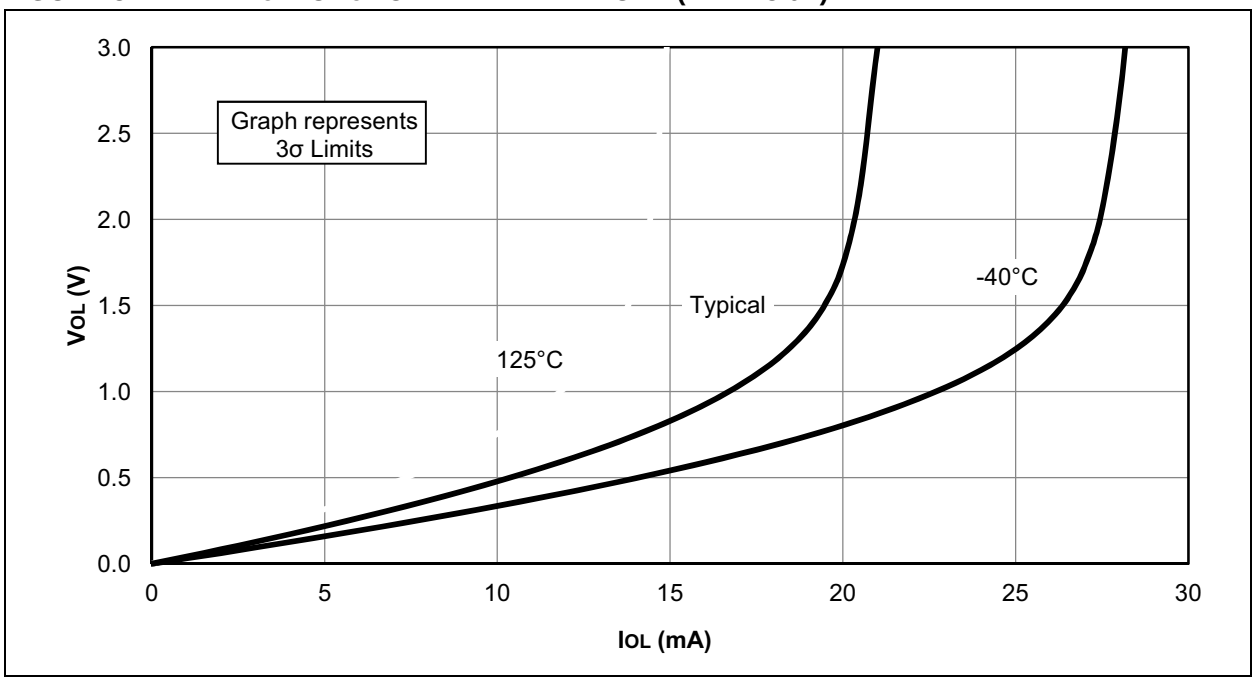


FIGURE 31-49: BROWN-OUT RESET VOLTAGE, BORV = 1

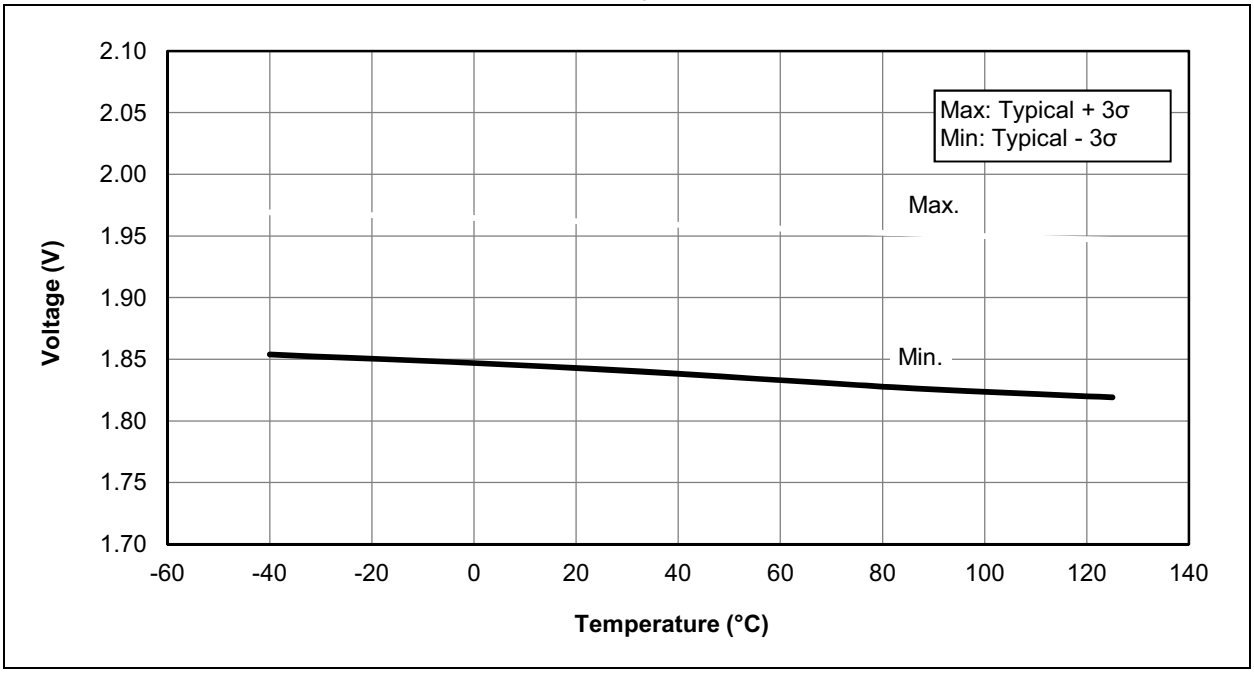
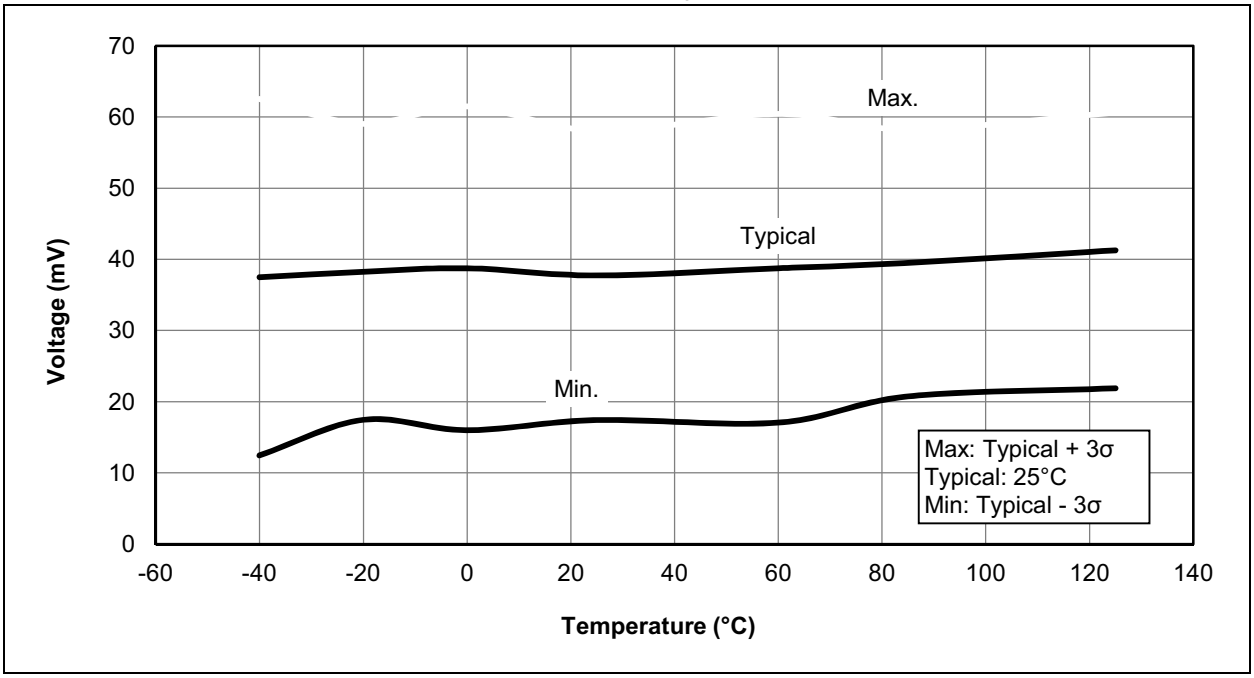
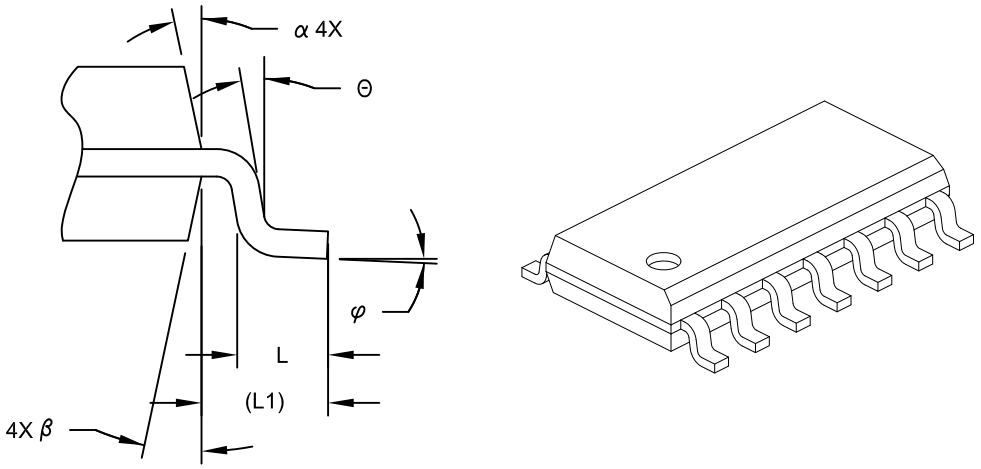


FIGURE 31-50: BROWN-OUT RESET HYSTERESIS, BORV = 1



14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

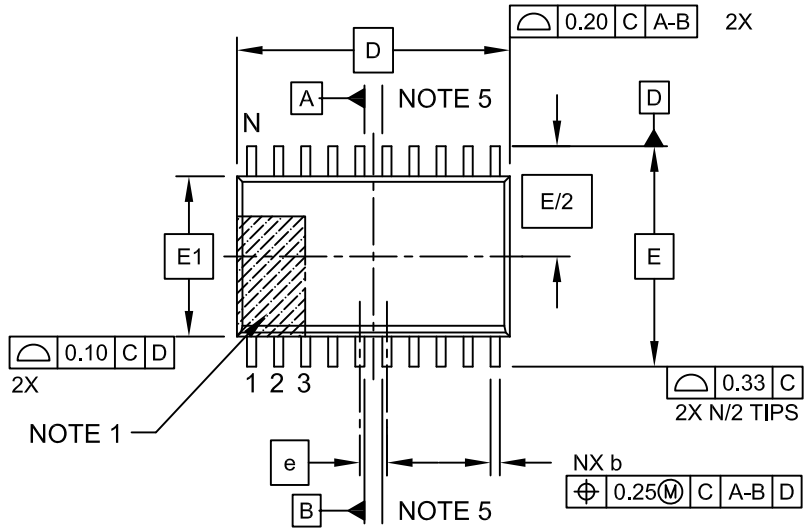
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

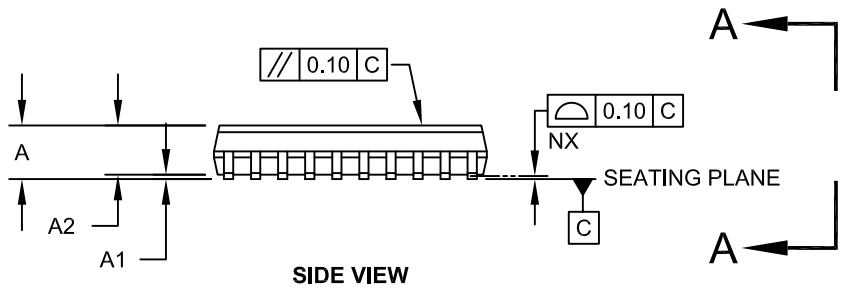
Microchip Technology Drawing No. C04-065C Sheet 2 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

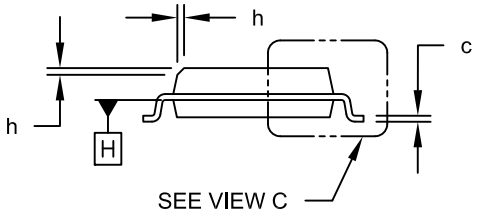
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

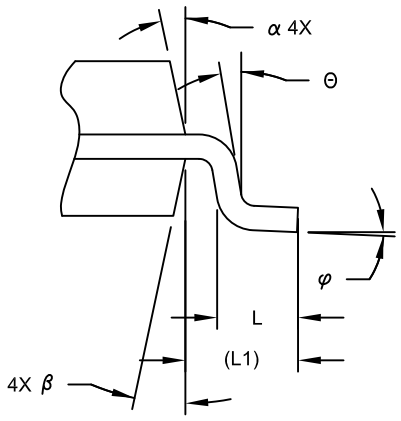


VIEW A-A

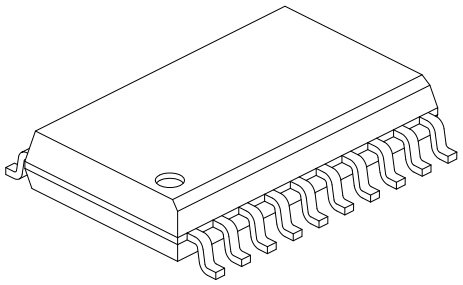
Microchip Technology Drawing C04-094C Sheet 1 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

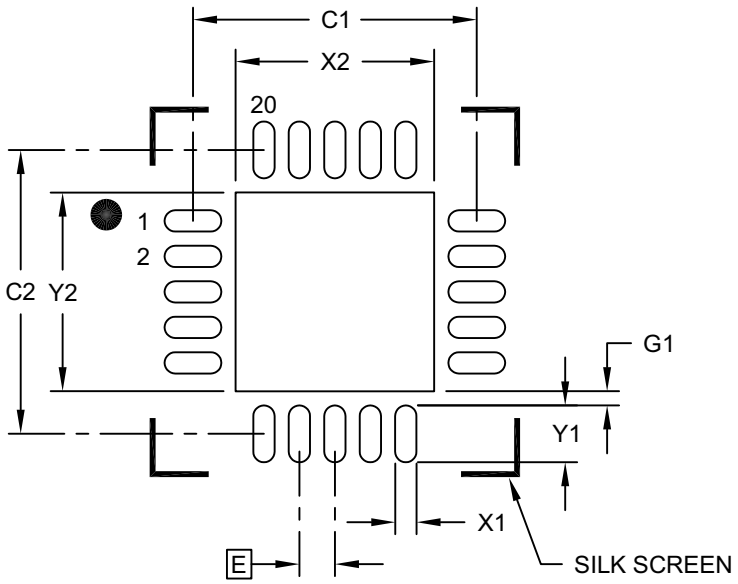
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			2.80
Optional Center Pad Length	Y2			2.80
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X20)	X1			0.30
Contact Pad Length (X20)	Y1			0.80
Contact Pad to Center Pad (X20)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2255A